

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wolfgang Hetzel et al. Examiner: Unknown
Serial No.: 10/577,173 Group Art Unit: Unknown
Filed: April 26, 2006 Docket: I431.156.101/FIN546PCT/US
Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING
COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND
METHOD FOR PRODUCING SAME

STATUS INQUIRY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

An application for the above-identified patent application was filed on April 26, 2006.

We have **not received any type of communication** at all.

Applicant as to the status of this application.

Any inquiries may be directed to Applicant's attorney, Mark L. Gleason, at (612) 767-2503.

Respectfully submitted,
Wolfgang Hetzel et al.,
By their attorneys,

Dated: 02/01/2008
MLG:cjs

/Mark L. Gleason/
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